

### REMARKS/ARGUMENTS

Favorable reconsideration of this application, in view of the present amendment and in light of the following discussion is respectfully requested.

Claims 1-34, 36, and 37 are pending. In the present amendment, Claims 1, 7, and 13 are currently amended. Support for the present amendment can be found in the original specification, for example, at page 38, lines 14-26, and in original Figures 1A-1E. Thus, it is respectfully submitted that no new matter is added.

In the outstanding Office Action, Claims 1, 5, 7-13, 17-19, 36, and 37 were rejected under 35 U.S.C. § 103(a) as unpatentable over Reinecke et al. (U.S. Patent No. 5,716,741, hereinafter “Reinecke”); and Claims 2-4, 6, and 14-16 were rejected under 35 U.S.C. § 103(a) as unpatentable over Reinecke in view of Hashimoto et al. (U.S. Patent No. 5,527,662, hereinafter “Hashimoto”).

In response to the rejections under 35 U.S.C. § 103(a), Applicants respectfully request reconsideration of these rejections and traverse these rejections, as discussed below.

Amended Claim 1 recites, in part, a process of producing a resin molded product comprising forming a resist pattern on a substrate. Additionally, the forming a resist pattern comprises forming a plurality of resist layers on the substrate. Further, *after the forming the plurality of resist layers*, developing the plurality of resist layers through solubility control in such a way that an upper resist layer has lower solubility in a developer than a lower resist layer to form the resist pattern. Thus, as can be seen in the exemplary embodiment shown in Figures 1A-1E, the portions of the first and second resist layers are developed *after both resist layers are formed* such that the resist pattern containing a groove with different depths is formed in a single developing step. It is respectfully submitted that the cited references do not disclose or suggest every feature recited in amended Claim 1.

Reinecke describes a method of producing stepped mould inserts and stepped microstructure bodies.<sup>1</sup> Specifically, according to Reinecke, a copper layer 9 is formed after exposing and removing the first resist layer 8.<sup>2</sup> Then, the portion of the first resist layer 8 which is not dissolved because it is masked in the exposure processing is removed, and then a new second resist layer 12 is formed.<sup>3</sup> At this time, the resist layer that is subjected to the exposure processing is only the secondly formed resist layer 12. Further, Reinecke describes using the resist layer 12 that has a different height as the copper layer 9.

However, it is respectfully submitted that Reinecke does not disclose or suggest “after the forming the plurality of resist layers, developing the plurality of resist layers through solubility control in such a way that an upper resist layer has lower solubility in a developer than a lower resist layer to form the resist pattern,” as recited in amended Claim 1.

Instead, as discussed above, the technique described in Reinecke is one in which the first resist layer is formed and then completely removed before forming a second resist layer. Thus, the first resist layer 8 is developed *before* the second resist layer 12 is formed, not after. Therefore, it is respectfully submitted that Reinecke neither discloses nor suggests that the two resist layers 8, 12 are deposited and exposed in one step. On the contrary, Reinecke only uses one resist layer at a time having different heights.

Further, it is respectfully submitted that Reinecke neither discloses nor suggests that the solubilities of the two resist layers 8, 12 are controlled with respect to one another, as there is no step of depositing the second resist layer 12 before a first resist layer 8 is completely removed. Accordingly, a person of ordinary skill in the art would not find it obvious to control the solubilities of the two resist layers based on the technique described in Reinecke.

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<sup>1</sup> See Reinecke, at column 1, lines 16-19.

<sup>2</sup> See Reinecke, at column 3, lines 9-25 and in Figures 1-4.

<sup>3</sup> See Reinecke, at column 3, lines 26-28, at column 9, lines 12-15, and in Figures 5 and 6.

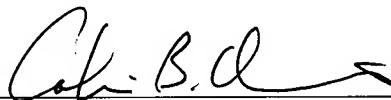
Therefore, it is respectfully submitted that Reinecke does not disclose or suggest every feature recited in amended Claim 1. Further, it is noted that independent Claims 7 and 13, while directed to alternative embodiments, each recite features similar to those discussed above with respect to Claim 1. Thus, it is respectfully requested that the rejection of Claims 1, 7, and 13, and all claims dependent thereon, as unpatentable over Reinecke be withdrawn.

Regarding the rejection of Claims 2-4, 6, and 14-16 as unpatentable over Reinecke in view of Hashimoto, it is noted that Claims 2-4, 6, and 14-16 are dependent on Claims 1 and 7, and thus are believed to be patentable for at least the reasons discussed above with respect to Claims 1 and 7. Further, it is respectfully submitted that Hashimoto does not cure the above-noted deficiencies of Reinecke. Accordingly, it is respectfully submitted that Claims 2-4, 6, and 14-16 are patentable over Reinecke in view of Hashimoto.

Consequently, in view of the present amendment, no further issues are believed to be outstanding in the present application and the present application is believed to be in condition for formal allowance. A Notice of Allowance is earnestly solicited.

Respectfully submitted,

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